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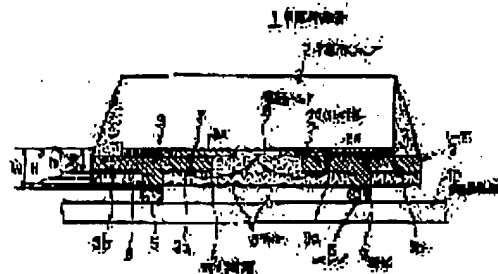
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(54) SEMICONDUCTOR DEVICE, MANUFACTURE THEREOF AND MANUFACTURE OF LEAD FRAME

(57)Abstract:

PURPOSE: To provide a semiconductor device having resin-sealed semiconductor chip and lead, manufacture thereof and manufacture of a lead frame used for the semiconductor device, wherein reliability of the semiconductor chip, standardization of an external electrode terminal, reduction in manufacturing cost and improvement in production efficiency may be realized.

CONSTITUTION: A semiconductor device has a semiconductor chip 2 having an electrode pad 6 at a first pitch, a lead 3 electrically connected with the electrode pad 6 via a wire 8, and seal resin 4 for sealing the semiconductor chip 2. In this semiconductor device, a protrusion 9 to be an external connection terminal is formed on the lead 3 at a second pitch different from the first pitch. The seal resin 4 seals the wire 8 arranged between the electrode pad 6 and the lead 3. Also, the protrusion 9 is exposed.

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